

The TRS3237E transmitters are disabled and the outputs are forced into high-impedance state when the device is in shutdown mode ($\overline{\text{SHDN}} = \text{GND}$) and the supply current falls to less than 1 μA . Also, during shutdown, the onboard charge pump is disabled; $V+$ is lowered to V_{CC} , and $V-$ is raised toward GND. Receiver outputs also can be placed in the high-impedance state by setting enable (EN) high. ROUT1B remains active all the time, regardless of the EN and SHDN condition.

The TRS3237EC is characterized for operation from 0°C to 70°C. The TRS3237EI is characterized for operation from –40°C to 85°C.

Table 1. ORDERING INFORMATION⁽¹⁾

T _A	PACKAGE ⁽²⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	SSOP – DB	Reel of 2000	TRS3237ECDBR	TRS3237EC
	SOIC – DW	Reel of 2000	TRS3237ECDWR	TRS3237EC
	TSSOP – PW	Reel of 2000	TRS3237ECPWR	RS37EC
	QFN – RHB	Reel of 2000	TRS3237ECRHBR	PREVIEW
–40°C to 85°C	SSOP – DB	Reel of 2000	TRS3237EIDBR	TRS3237EI
	SOIC – DW	Reel of 2000	TRS3237EIDWR	TRS3237EI
	TSSOP – PW	Reel of 2000	TRS3237EIPWR	RS37EI
	QFN – RHB	Reel of 2000	TRS3237EIRHBR	PREVIEW

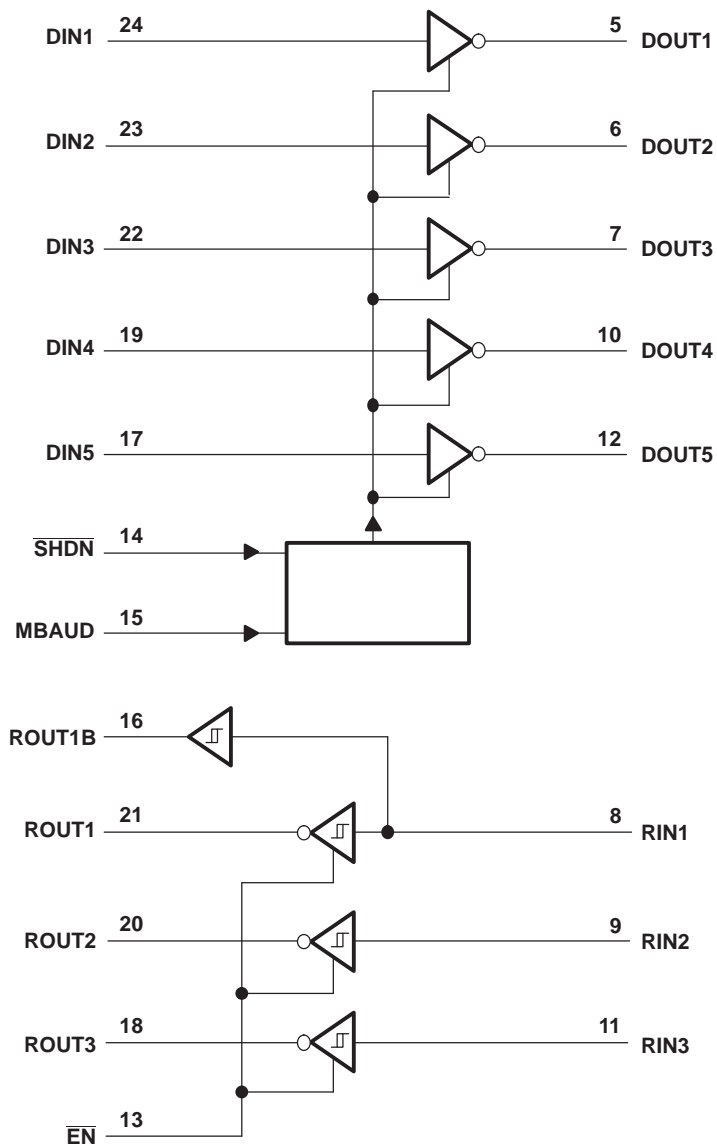
- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
- (2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

Table 2. FUNCTION TABLE

INPUTS		OUTPUTS		
$\overline{\text{SHDN}}$	$\overline{\text{EN}}$	DOUT	ROUT	ROUT1B
0	0	Z ⁽¹⁾	Active	Active
0	1	Z ⁽¹⁾	Z ⁽¹⁾	Active
1	0	Active	Active	Active
1	1	Active	Z ⁽¹⁾	Active

(1) Z = high impedance (off)

LOGIC DIAGRAM (POSITIVE LOGIC)



ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT	
V _{CC}	Supply voltage range ⁽²⁾	-0.3	6	V	
V+	Positive-output supply voltage range ⁽²⁾	-0.3	7	V	
V-	Negative-output supply voltage range ⁽²⁾	0.3	-7	V	
V+ - V-	Supply voltage difference ⁽²⁾		13	V	
V _I	Input voltage range	Driver ($\overline{\text{SHDN}}$, MBAUD, $\overline{\text{EN}}$)	-0.3	6	V
		Receiver	-25	25	
V _O	Output voltage range	Driver	-13.2	13.2	V
		Receiver	-0.3	V _{CC} + 0.3	
	Short-circuit duration	DOUT to GND		Unlimited	
θ _{JA}	Package thermal impedance ⁽³⁾		62	°C/W	
T _{stg}	Storage temperature range	-65	150	°C	

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltages are with respect to network GND.
- (3) The package thermal impedance is calculated in accordance with JESD 51-7.

RECOMMENDED OPERATING CONDITIONS⁽¹⁾

See [Figure 5](#)

		MIN	NOM	MAX	UNIT	
Supply voltage		V _{CC} = 3.3 V	3	3.3	3.6	V
		V _{CC} = 5 V	4.5	5	5.5	
V _{IH}	Driver and control high-level input voltage	DIN, $\overline{\text{SHDN}}$, MBAUD, $\overline{\text{EN}}$	V _{CC} = 3.3 V	2	5.5	V
			V _{CC} = 5 V	2.4	5.5	
V _{IL}	Driver and control low-level input voltage	DIN, $\overline{\text{SHDN}}$, MBAUD, $\overline{\text{EN}}$		0	0.8	V
V _I	Receiver input voltage	-25		25	V	
T _A	Operating free-air temperature	TRS3237EC	0	70	°C	
		TRS3237EI	-40	85		

- (1) Test conditions are C1–C4 = 0.1 μF at V_{CC} = 3 V to 5 V.

ELECTRICAL CHARACTERISTICS⁽¹⁾

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 5](#))

PARAMETER		TEST CONDITIONS	MIN	TYP ⁽²⁾	MAX	UNIT	
I _I	Input leakage current	DIN, $\overline{\text{SHDN}}$, MBAUD, $\overline{\text{EN}}$		9	18	μA	
I _{CC}	Supply current (T _A = 25°C)	No load, $\overline{\text{SHDN}} = V_{CC}$		0.5	2	mA	
		Shutdown supply current	$\overline{\text{SHDN}} = \text{GND}$		1	10	μA
			$\overline{\text{SHDN}} = \text{RIN} = \text{GND}$, DIN = GND or V _{CC}		10	300	nA

- (1) Test conditions are C1–C4 = 0.1 μF at V_{CC} = 3 V to 5 V.
- (2) All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

DRIVER SECTION ELECTRICAL CHARACTERISTICS⁽¹⁾

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 5](#))

PARAMETER		TEST CONDITIONS		MIN	TYP ⁽²⁾	MAX	UNIT
V _{OH}	High-level output voltage	DOUT at R _L = 3 kΩ to GND,	DIN = GND	5	5.4		V
V _{OL}	Low-level output voltage	DOUT at R _L = 3 kΩ to GND,	DIN = V _{CC}	-5	-5.4		V
I _{IH}	High-level input current	V _I = V _{CC}		±0.01		±1	μA
I _{IL}	Low-level input current	V _I at GND		±0.01		±1	μA
I _{OS}	Short-circuit output current ⁽³⁾	V _{CC} = 3.6 V or 3.3 V,	V _O = 0 V			±60	mA
r _o	Output resistance	V _{CC} , V ₊ , and V ₋ = 0 V,	V _O = ±2 V	300	50k		Ω

(1) Test conditions are C1–C4 = 0.1 μF at V_{CC} = 3 V to 5 V.

(2) All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

(3) Short-circuit durations should be controlled to prevent exceeding the device absolute power-dissipation ratings, and not more than one output should be shorted at a time.

DRIVER SECTION SWITCHING CHARACTERISTICS⁽¹⁾

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 5](#))

PARAMETER		TEST CONDITIONS		MIN	TYP ⁽²⁾	MAX	UNIT
Maximum data rate		C _L = 1000 pF, MBAUD = GND	R _L = 3 kΩ, 1 DIN switching, See Figure 1	250			kbit/s
		C _L = 1000 pF, V _{CC} = 4.5 V to 5.5 V, MBAUD = V _{CC}		1000			
		C _L = 250 pF, V _{CC} = 3 V to 4.5 V, MBAUD = V _{CC}		1000			
t _{sk(p)}	Pulse skew ⁽³⁾	C _L = 150 pF to 2500 pF, R _L = 3 kΩ to 7 kΩ, MBAUD = V _{CC} or GND, See Figure 2			100		ns
SR(tr)	Slew rate, transition region (see Figure 1)	V _{CC} = 3.3 V, R _L = 3 kΩ to 7 kΩ, T _A = 25°C	C _L = 150 pF to 1000 pF	MBAUD = GND	6	30	V/μs
				MBAUD = V _{CC}	24	150	
			C _L = 150 pF to 2500 pF,	MBAUD = GND	4	30	

(1) Test conditions are C1–C4 = 0.1 μF at V_{CC} = 3 V to 5 V.

(2) All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

(3) Pulse skew is defined as |t_{PLH} – t_{PHL}| of each channel of the same device.

RECEIVER SECTION ELECTRICAL CHARACTERISTICS⁽¹⁾

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 5](#))

PARAMETER		TEST CONDITIONS	MIN	TYP ⁽²⁾	MAX	UNIT
V _{OH}	High-level output voltage	I _{OH} = -1 mA	V _{CC} - 0.6	V _{CC} - 0.1		V
V _{OL}	Low-level output voltage	I _{OL} = 1 mA			0.4	V
V _{IT+}	Positive-going input threshold voltage	V _{CC} = 3.3 V		1.5	2.4	V
		V _{CC} = 5 V		2	2.4	
V _{IT-}	Negative-going input threshold voltage	V _{CC} = 3.3 V	0.6	1.1		V
		V _{CC} = 5 V	0.8	1.5		
V _{hys}	Input hysteresis (V _{IT+} - V _{IT-})			0.5		V
I _{oz}	Output leakage current	$\overline{EN} = V_{CC}$		±0.05	±10	µA
r _i	Input resistance	V _i = ±3 V to ±25 V	3	5	7	kΩ

- (1) Test conditions are C1–C4 = 0.1 mF at V_{CC} = 3 V to 5 V.
- (2) All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

RECEIVER SECTION SWITCHING CHARACTERISTICS⁽¹⁾

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

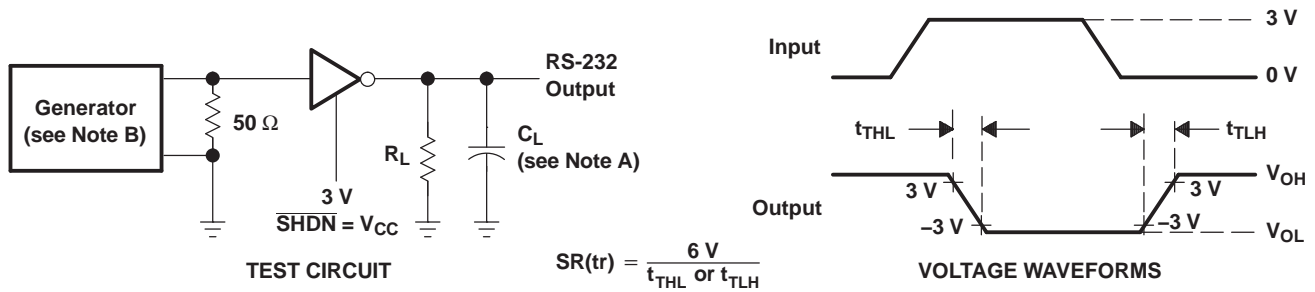
PARAMETER		TEST CONDITIONS	TYP ⁽²⁾	UNIT
t _{PLH}	Propagation delay time, low- to high-level output	C _L = 150 pF, See Figure 3	150	ns
t _{PHL}	Propagation delay time, high- to low-level output	C _L = 150 pF, See Figure 3	150	ns
t _{en}	Output enable time	C _L = 150 pF, R _L = 3 kΩ, See Figure 4	2.6	µs
t _{dis}	Output disable time	C _L = 150 pF, R _L = 3 kΩ, See Figure 4	2.4	µs
t _{sk(p)}	Pulse skew ⁽³⁾	See Figure 3	50	ns

- (1) Test conditions are C1–C4 = 0.1 µF at V_{CC} = 3 V to 5 V.
- (2) All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.
- (3) Pulse skew is defined as |t_{PLH} - t_{PHL}| of each channel of the same device.

ESD PROTECTION

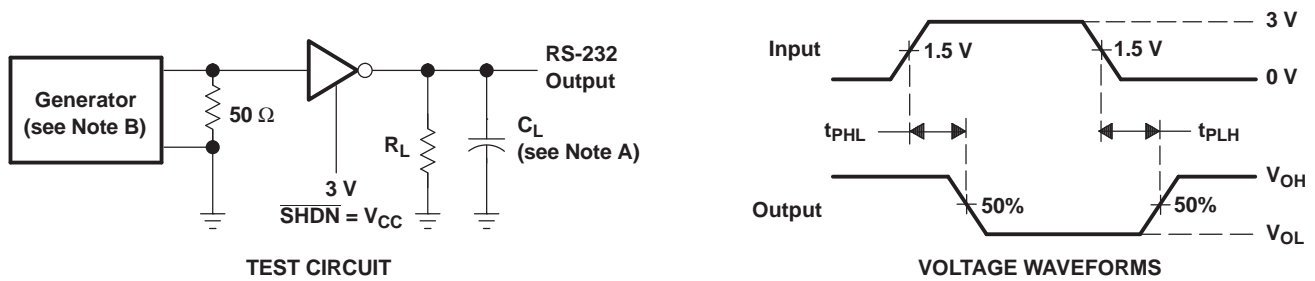
PIN	TEST CONDITIONS	TYP	UNIT
DOUT, RIN	IEC61000-4-2, Contact Discharge	±8	kV
	IEC61000-4-2, Air-Gap Discharge	±15	

PARAMETER MEASUREMENT INFORMATION



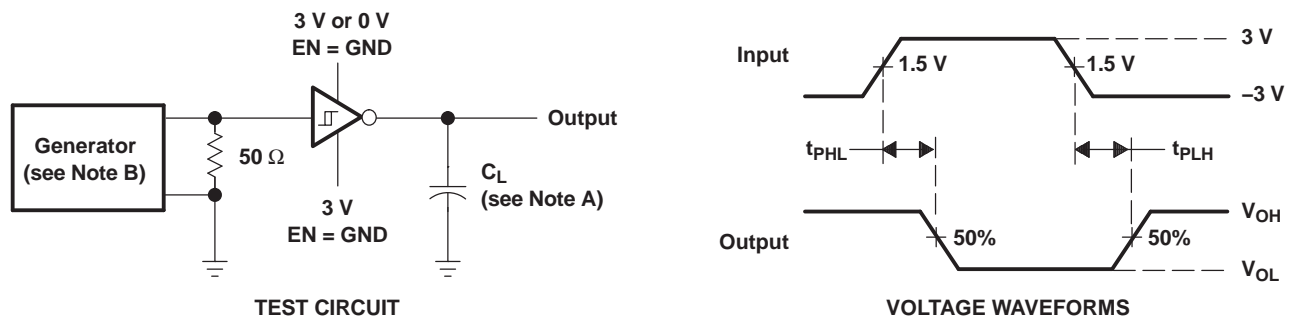
NOTES: A. C_L includes probe and jig capacitance.
 B. The pulse generator has the following characteristics: PRR = 250 kbit/s, Z_O = 50 Ω, 50% duty cycle, t_r ≤ 10 ns, t_f ≤ 10 ns.

Figure 1. Driver Slew Rate



NOTES: A. C_L includes probe and jig capacitance.
 B. The pulse generator has the following characteristics: PRR = 250 kbit/s, Z_O = 50 Ω, 50% duty cycle, t_r ≤ 10 ns, t_f ≤ 10 ns.

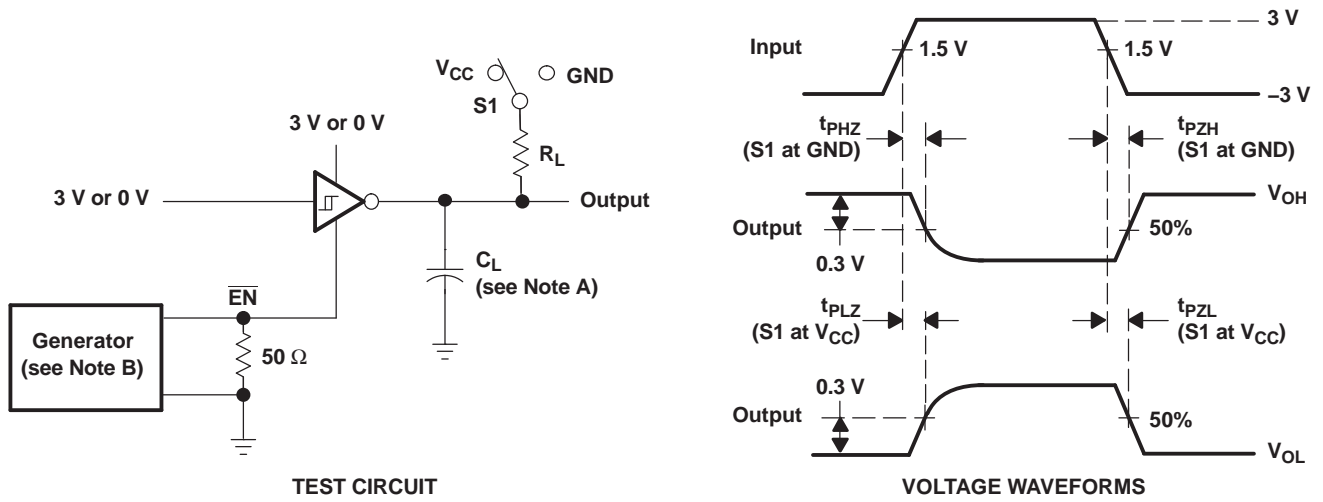
Figure 2. Driver Pulse Skew



NOTES: A. C_L includes probe and jig capacitance.
 B. The pulse generator has the following characteristics: Z_O = 50 Ω, 50% duty cycle, t_r ≤ 10 ns, t_f ≤ 10 ns.

Figure 3. Receiver Propagation Delay Times

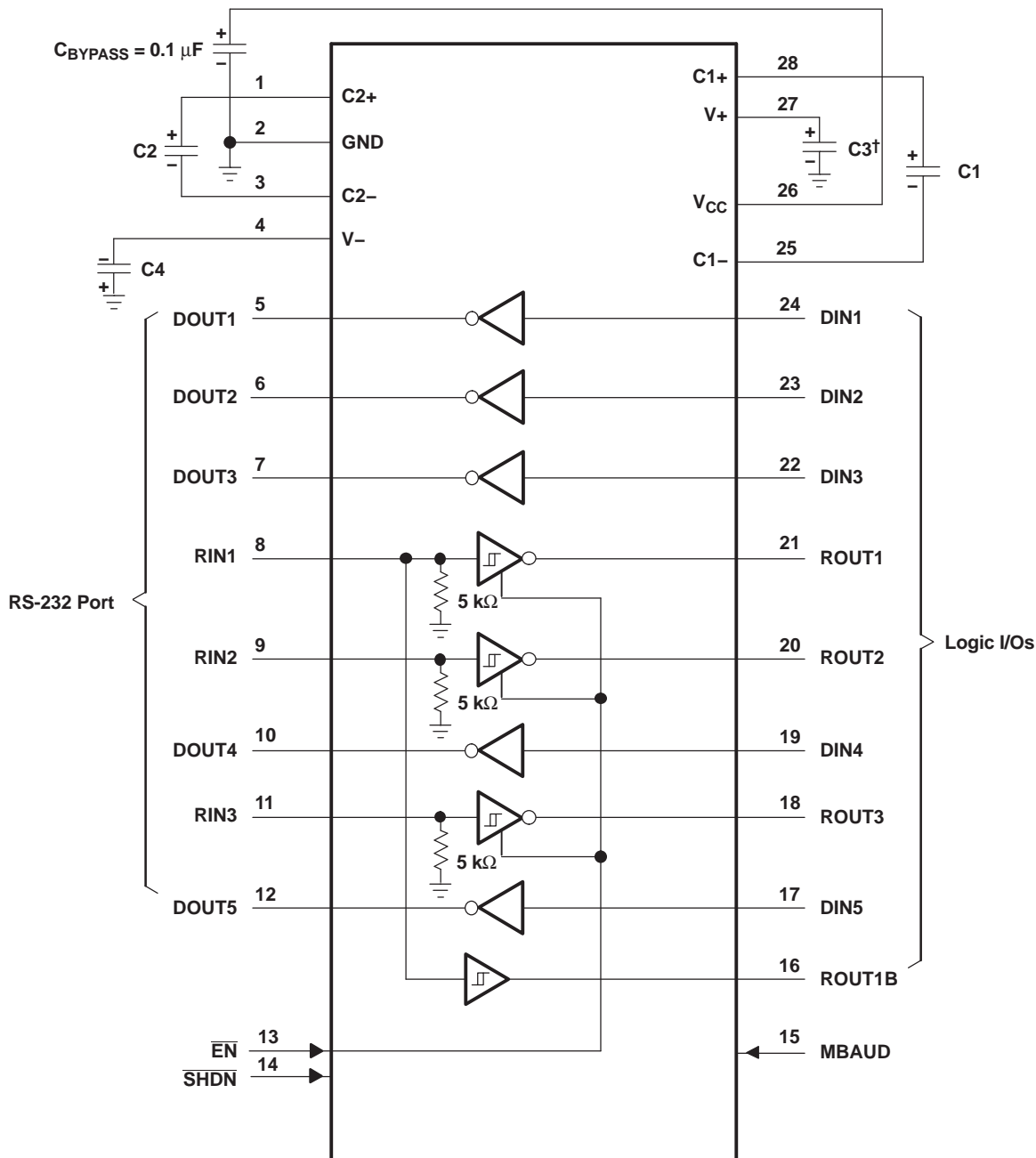
PARAMETER MEASUREMENT INFORMATION (continued)



- NOTES: A. C_L includes probe and jig capacitance.
 B. The pulse generator has the following characteristics: $Z_O = 50 \Omega$, 50% duty cycle, $t_r \leq 10 \text{ ns}$, $t_f \leq 10 \text{ ns}$.
 C. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 D. t_{PZL} and t_{PZH} are the same as t_{en} .

Figure 4. Receiver Enable and Disable Times

APPLICATION INFORMATION



† C3 can be connected to V_{CC} or GND.

NOTES: A. Resistor values shown are nominal.

B. Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they should be connected as shown.

V_{CC} vs CAPACITOR VALUES

V _{CC}	C1	C2, C3, and C4
3.3 V ± 0.15 V	0.1 μF	0.1 μF
3.3 V ± 0.3 V	0.22 μF	0.22 μF
5 V ± 0.5 V	0.047 μF	0.33 μF
3 V to 5.5 V	0.22 μF	1 μF

Figure 5. Typical Operating Circuit and Capacitor Values

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TRS3237ECDBR	Active	Production	SSOP (DB) 28	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TRS3237EC
TRS3237ECDBR.A	Active	Production	SSOP (DB) 28	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TRS3237EC
TRS3237ECPWR	Obsolete	Production	TSSOP (PW) 28	-	-	Call TI	Call TI	0 to 70	RS37EC
TRS3237EIDB	Obsolete	Production	SSOP (DB) 28	-	-	Call TI	Call TI	-40 to 85	TRS3237EI
TRS3237EIDBR	Active	Production	SSOP (DB) 28	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TRS3237EI
TRS3237EIDBR.A	Active	Production	SSOP (DB) 28	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TRS3237EI
TRS3237EIDBRG4	Active	Production	SSOP (DB) 28	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TRS3237EI
TRS3237EIDBRG4.A	Active	Production	SSOP (DB) 28	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TRS3237EI
TRS3237EIPWR	Active	Production	TSSOP (PW) 28	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	RS37EI
TRS3237EIPWR.A	Active	Production	TSSOP (PW) 28	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	RS37EI

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TRS3237ECDBR	SSOP	DB	28	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
TRS3237EIDBR	SSOP	DB	28	2000	330.0	16.4	8.45	10.55	2.5	12.0	16.2	Q1
TRS3237EIDBRG4	SSOP	DB	28	2000	330.0	16.4	8.45	10.55	2.5	12.0	16.2	Q1
TRS3237EIPWR	TSSOP	PW	28	2000	330.0	16.4	6.9	10.2	1.8	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS

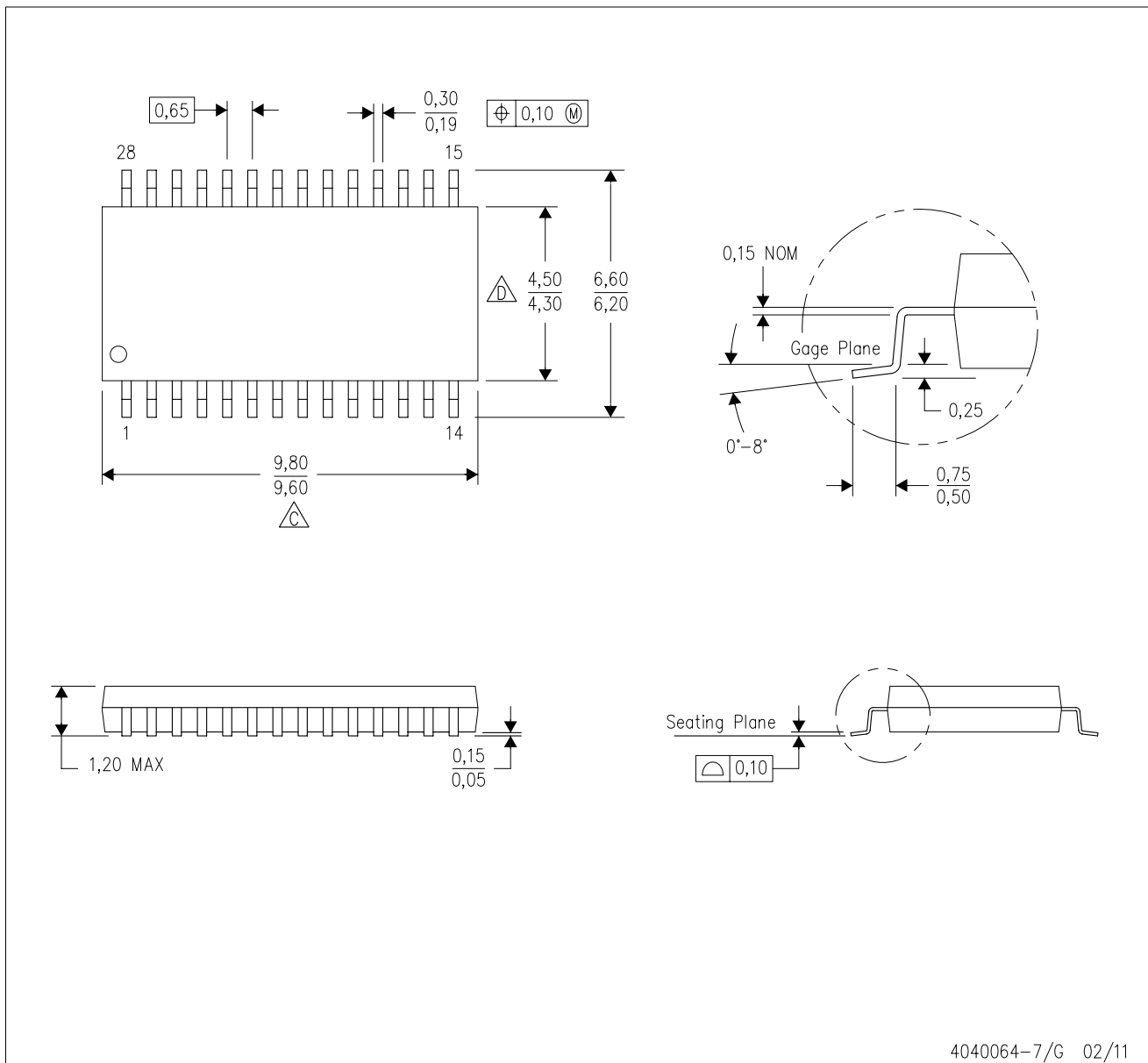


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TRS3237ECDBR	SSOP	DB	28	2000	356.0	356.0	35.0
TRS3237EIDBR	SSOP	DB	28	2000	356.0	356.0	35.0
TRS3237EIDBRG4	SSOP	DB	28	2000	356.0	356.0	35.0
TRS3237EIPWR	TSSOP	PW	28	2000	356.0	356.0	35.0

PW (R-PDSO-G28)

PLASTIC SMALL OUTLINE



4040064-7/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

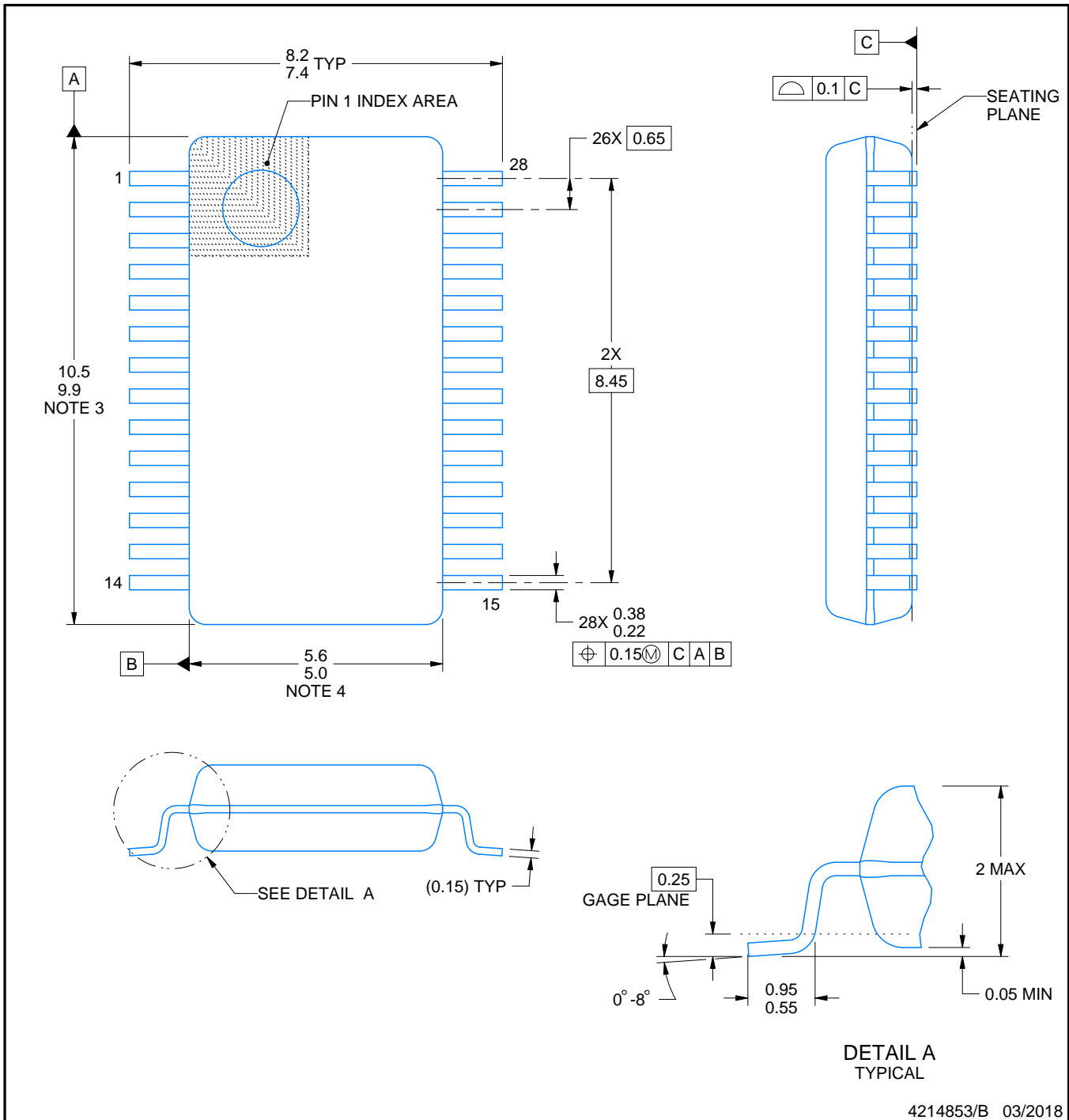
DB0028A



PACKAGE OUTLINE

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



4214853/B 03/2018

NOTES:

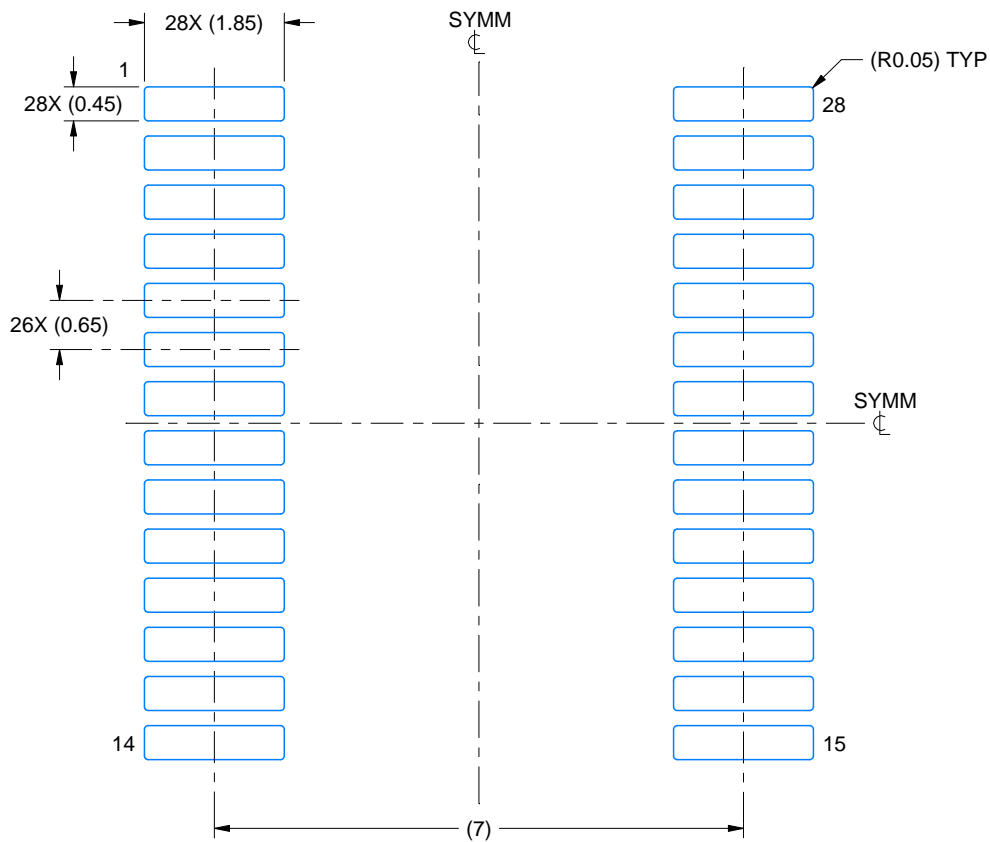
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-150.

EXAMPLE BOARD LAYOUT

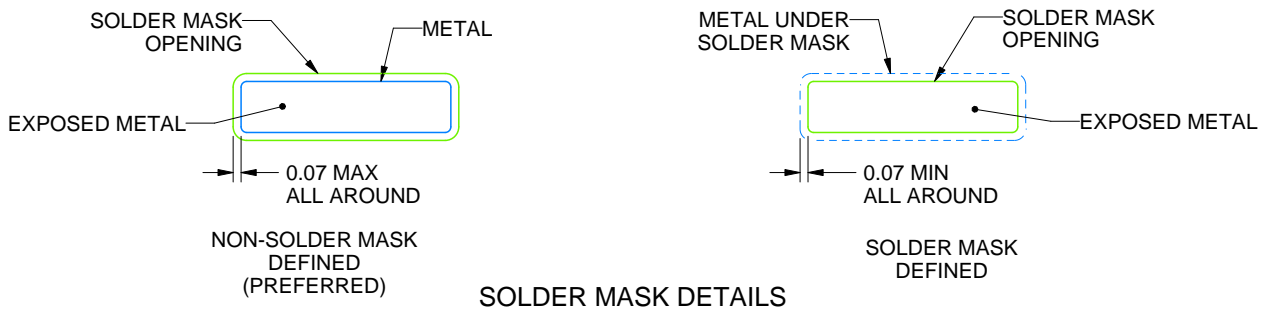
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SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4214853/B 03/2018

NOTES: (continued)

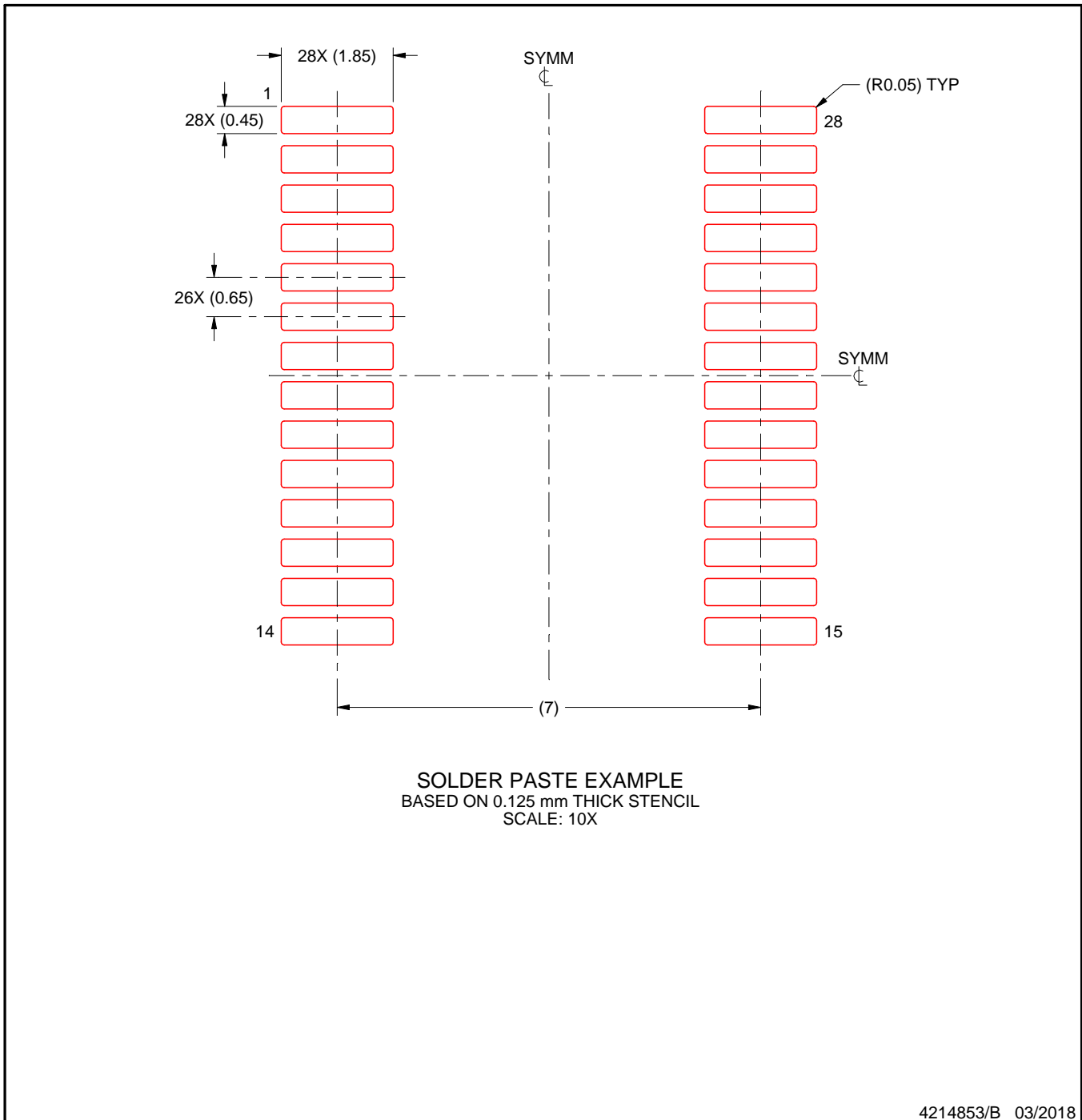
- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0028A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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